



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Herald M. Baldonado
Serial No.: 10/066,421
Filed: 01/30/2002
For: Method and System of Wire Bonding Using Interposer Pads

TI No.: 32857
Art Unit: 2815
Examiner: Clark, Sheila
Conf. No.: 5110

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NOTICE OF APPEAL

Commissioner For Patents
Alexandria, VA 22313-1450

Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the US Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, Alexandria, VA 22313-1450

Elizabeth Austin

Date

Applicant hereby appeals to the Board of Appeals from the decision dated , of the Primary Examiner finally rejecting Claims .

Charge the fee of \$320.00 to the deposit account of Texas Instruments Incorporated, Account No. 20-0668. An original and two copies of this sheet are enclosed.

Respectfully submitted,

Michael K. Skrehot

Attorney for Applicant

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